



Appl. No. 09/784,234

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. 09/784,234
Filing Date February 14, 2001
Inventor..... Shozo Nagano et al.
Assignee..... Honeywell International Inc.
Group Art Unit..... 1742
Examiner Ip, Sikyin
Attorney's Docket No. 30-5000-DIV1
Title: Conductive Integrated Circuit Metal Alloy Interconnections, Electroplating Anodes,
Metal Alloys For Use As A Conductive Interconnection In An Integrated Circuit, and
Physical Vapor Deposition Targets

**RESPONSE TO NOVEMBER 18, 2003 FINAL ACTION AND FEBRUARY 5, 2004
ADVISORY ACTION ACCOMPANYING FILING OF AN RCE**

To: Mail Stop RCE
Commissioner for Patents
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AMENDMENTS

Introductory Comments

In reply to the Final Office Action dated November 18, 2003, and the subsequent
Advisory Action, applicant amends and remarks as follows.